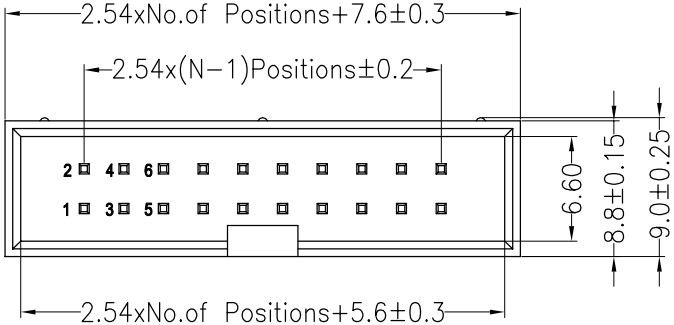
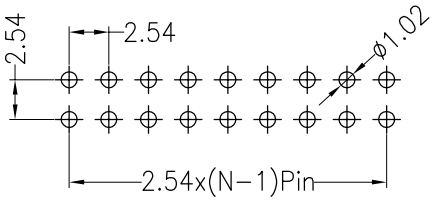
HSF RoHS

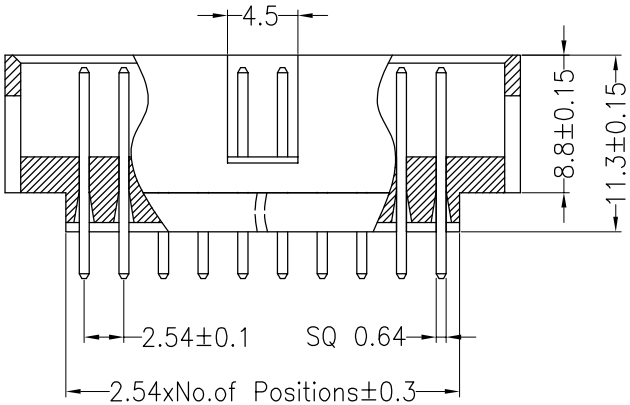
SPECIFICATIONS
Rated Current:3.0AMP
Contact Resistance:20mΩ Max
Withstand Voltage:1000V AC/DC
Insulation Resistance:1000MΩ Min
Operation Temperature:−40°c to +105°c

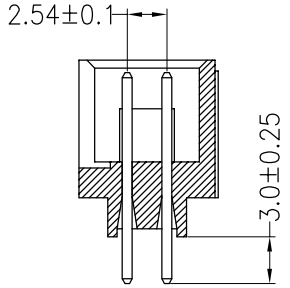
Contact Material:Brass
Contact Plating:Au or Sn Over Ni
Insulator Material:Polyester(UL94V−0)
Standard: PA6T
Max.Processing Temp: 230°C for 30−60 seconds
(260°C for 10 seconds)



Recommended P.C.B Layout(Top Side)
(PCB BOARD TOLERANCE±0.05)







Ordering Information

3218 XX S XX X B K00 X 0X

- XX: No.of Pins 6−−64
- XX: Contact Plating
  G0:Gold Flash
  G1:1U" Gold
  G2:1.5U" Gold
  G3:2U" Gold
  G4:3U" Gold
  G5:5U" Gold
  S0:Gold Flash/Tin
  SN:Tin
- X: Insulator Material Option
  A=BK−PBT
  C=BK−PA6T
  D=BK−PA46
  E=BK−PA9T
  F=BK−LCP
- X: Packing
  0=PE Bag
  A=Tray
  T=Tube

REV	DATE	MODIFICATION DESCRIPTION	CHANGE
A0	2018.10.05	NEW DRAWING	

OPERATION		DRAW	Liu Miao	18.10.05	SCALE	FIT
X.X	±0.30				UNIT	mm
X.XX	±0.20	CHECK			SIZE	A4
X.XXX	±0.10				SHEET	1/1
Angle	±3°	APPROVE			PROJ.	
DIM	TOL					

WFD CONN 深圳市旺富达电子有限公司 SHEN ZHEN WFD ELECTRONICS CO., LTD

PART NO.	3218XXSXXXBK00X0X
TITLE:	2.54mm Box Header H11.3 180°